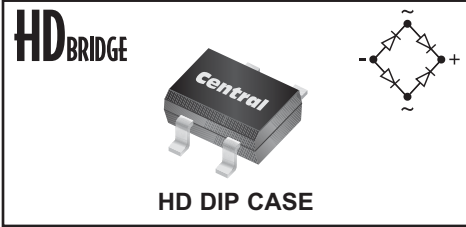


CBRHDSH2-100
SURFACE MOUNT
HIGH DENSITY
2 AMP SILICON
SCHOTTKY BRIDGE RECTIFIER



• Device is **Halogen Free** by design



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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CBRHDSH2-100 is a full wave bridge rectifier mounted in a durable epoxy surface mount case, utilizing glass passivated chips.

MARKING CODE: CSH10

FEATURES:

- Low Leakage Current (700nA TYP @ V_{RRM})
- High 2.0A Current Rating
- Low V_F Schottky Diodes (840mV MAX @ $I_F=2.0A$)

MAXIMUM RATINGS: ($T_A=25^{\circ}C$ unless otherwise noted)		SYMBOL		UNITS
Peak Repetitive Reverse Voltage		V_{RRM}	100	V
DC Blocking Voltage		V_R	100	V
RMS Reverse Voltage		$V_{R(RMS)}$	70	V
Average Forward Current ($T_A=75^{\circ}C$)		I_O	2.0	A
Peak Forward Surge Current (8.3ms)		I_{FSM}	50	A
Operating Junction Temperature		T_J	-50 to +125	$^{\circ}C$
Storage Temperature		T_{stg}	-50 to +150	$^{\circ}C$

ELECTRICAL CHARACTERISTICS PER DIODE: ($T_A=25^{\circ}C$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	TYP	MAX	UNITS
I_R	$V_R=100V$	0.70	4.0	μA
V_F	$I_F=500mA$	610		mV
V_F	$I_F=1.0A$	700		mV
V_F	$I_F=2.0A$	770	840	mV
C_J	$V_R=4.0V, f=1.0MHz$		250	pF

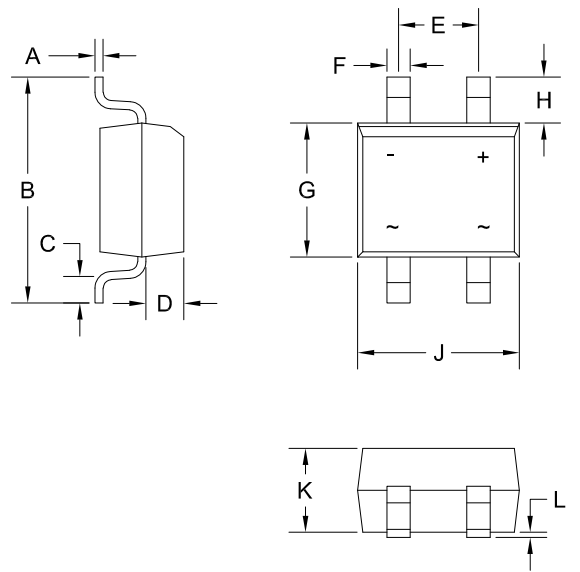
R4 (19-August 2020)

CBRHDSH2-100

SURFACE MOUNT
HIGH DENSITY
2 AMP SILICON
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HD DIP CASE - MECHANICAL OUTLINE



R3

SYMBOL	DIMENSIONS			
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.006	0.014	0.15	0.35
B	-	0.275	-	7.00
C	0.027	0.043	0.70	1.10
D	0.035	0.051	0.90	1.30
E	0.090	0.106	2.30	2.70
F	0.019	0.031	0.50	0.80
G	0.146	0.165	3.70	4.20
H	0.051	0.067	1.30	1.70
J	0.177	0.193	4.50	4.90
K	0.090	0.106	2.30	2.70
L	0.000	0.008	0.00	0.20

HD DIP (REV: R3)

MARKING CODE: CSH10

R4 (19-August 2020)

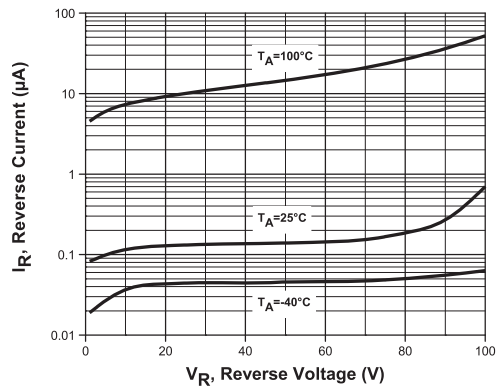
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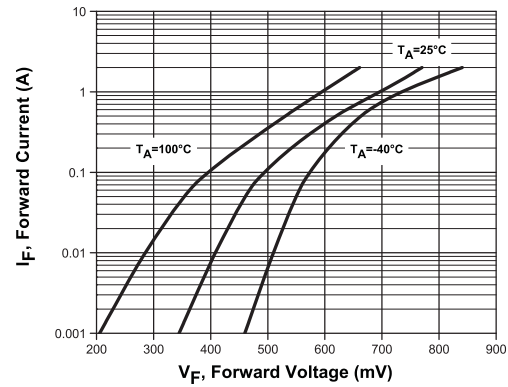


TYPICAL ELECTRICAL CHARACTERISTICS

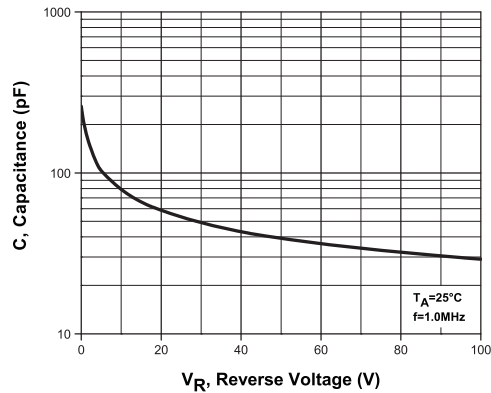
Typical Per Diode Leakage Current



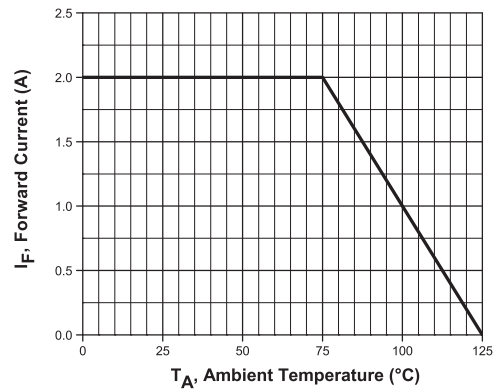
Typical Per Diode Forward Voltage



Typical Per Diode Capacitance



Per Diode Current Derating



R4 (19-August 2020)

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OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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